

PI74LVTCH244

3.3V 8-Bit Buffers/Line Drivers with 3-State Outputs

Product Features

- Advanced low power CMOS design for 2.7V to 3.6V Vcc operation
- Supports 5V input/output tolerance in mixed signal mode operation
- Function compatible with LVT family of products
- Balanced ±24mA output drive
- Typical V_{OLP} (Output Ground Bounce) < 0.8V at V_{CC}=3.3V, T_A=25°C
- I_{off} and Power Up/Down 3-State support live insertion
- Latch-up performance exceeds 200mA Per JESD78
- Bus Hold on data inputs eliminates the need for external pull-up/down resistors
- ESD protection exceeds JESD 22
 - -2000V Human-Body Model (A114-B)
 - -200V Machine Model (A115-A)
- Packages(Pb-free Available):
 - 20-pin 209-mil wide plastic SSOP (H20)
 - -20-pin 173-mil wide plastic TSSOP (L20)
 - -20-pin 300-mil wide plastic SOIC (S20)

Product Description

Pericom Semiconductor's PI74LVTC series of logic circuits are produced using the Company's advanced CMOS technology, achieving industry leading speed.

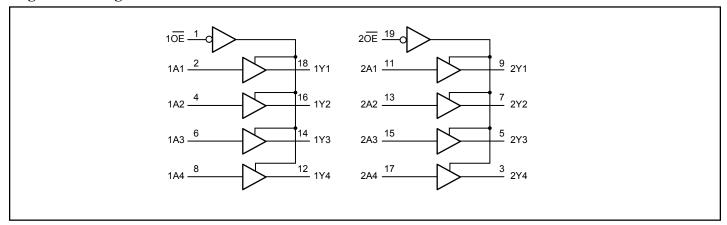
The PI74LVTCH244 is a non-inverting 8-bit buffer and line driver designed for low-voltage 2.7V to 3.6V $V_{\rm CC}$ operation, with the capability of interfacing to the 5V system environment. With its balanced drive characteristics, this high-speed, low power device provides low ground bounce and transmission line impedance matching. This makes it ideal for driving on board buses and transmission lines. The device can be used as two 4-bit buffers with separate output enable $(\overline{\rm OE})$ inputs.

The PI74LVTCH244 has "Bus Hold" which retains the data input's last valid logic state whenever the data input goes to high-impedance, preventing "floating" inputs and eliminating the need for pulup/down resistors.

When Vcc is between 0 to 1.5V during power up or power down, the outputs of the device are in the high-impedance state. To ensure the high-impedance state above 1.5V, \overline{OE} should be tied to Vcc through a pullup resistor; the minimum value of the resistor is determined by the current sinking capability of the driver.

The device fully supports live-insertion with its $I_{\rm off}$ and power-up/down 3-state. The $I_{\rm off}$ circuitry disables the outputs when the power is off, preventing the backflow of damaging current through the device. Power-up/down 3-state places the outputs in the high-impedance state during power up or power down, preventing driver conflict.

Logic Block Diagram



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Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Supply voltage range, V _{CC} 0.5V to +6.5V
Input voltage range, $V_I^{(1)}$ $-0.5V$ to $+6.5V$
Voltage range applied to any output in the
high-impedance or power-off state, $V_0^{(1)}$ $-0.5V$ to $+6.5V$
Voltage range applied to any output in the
active state, $V_0^{(1),(2)}$ 0.5V to V_{CC} +0.5V
Input clamp current, $I_{IK}(V_I < 0)$
Output clamp current, I _{OK} (V _O <0) –50mA
Continous Output Current I _O ±50mA
Continous Current through each V _{CC} or GND pin ±100mA
Package thermal impedance, $\theta_{JA}^{(2)}$: package H
package L 84°C/W
package S 84°C/W
Storage Temperature range, T _{stg} 65°C to 150°C

Notes:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

- 1. Input negative-voltage and output voltage ratings may be exceeded if the input and output clamp current ratings are observed.
- 2. This value is limited to 6.5V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

Truth Table⁽⁴⁾

Inp	Outputs	
x OE	xAx	xYx
L	Н	Н
L	L	L
Н	X	Z

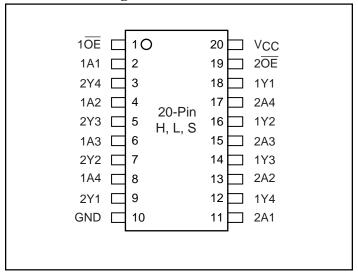
Notes:

- 4. H = High Signal Level
 - L = Low Signal Level
 - X = Don't Care or Irrelevant
 - Z = High Impedance

Product Pin Description

Pin Name	Description
xOE	3-State Output Enable Inputs (Active LOW)
xAx	Inputs
xYx	3-State Outputs
GND	Ground
V _{CC}	Power

Product Pin Configuration





$\textbf{Recommended Operating Conditions}^{(5)}$

		Min.	Max.	Units	
V _{CC} Supply Voltage	Operating	2.7	3.6	-	
V _{IH} High-level Input Voltage	$V_{CC} = 2.7V \text{ to } 3.6V$	2.0			
$V_{ m IL}$ Low-level Input Voltage	$V_{CC} = 2.7V \text{ to } 3.6V$		0.8		
V _I Input Voltage		0	5.5	V	
V Output Voltage	High or Low State	0	V _{CC}		
V _O Output Voltage	3-State	0	5.5		
I _{OH} High-level output current	$V_{CC} = 2.7V$		-12		
	$V_{CC} = 3.0 V \text{ to } 3.6 V$		- 24	A	
L. L. Louy lovel output output	$V_{CC} = 2.7V$		12	mA	
I _O L Low-level output current	$V_{CC} = 3.0 V \text{ to } 3.6 V$		24		
Δt/ΔV Input transition rise or fall rate			10	ns/V	
$\Delta t/\Delta V_{CC}$ Power-up ramp rate		150		μs/V	
T _A Operating free-air temperature		- 40	85	°C	

Notes: 5. All unused inputs must be held at V_{CC} or GND to ensure proper device operation.

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DC Electrical Characteristics (Over the Operating Range, T_A = -40°C+85°C)

Parameters	Description		Te	Test Conditions		Max.	Units	
V _{IK}	Clamp Diode V	/oltage	$V_{CC} = 2.7V$	$I_{I} = -18\text{mA}$		-1.2V		
			$V_{CC} = 2.7V \text{ to } 3.6V$	$I_{OH} = -100\mu A$	V _{CC} -0.2V			
* 7	Output High Vo	oltage	$V_{CC} = 2.7V$	$I_{OH} = -12\text{mA}$	2.2		1	
V_{OH}		C	V - 2V	$I_{OH} = -12\text{mA}$	2.4			
			$V_{CC} = 3V$	$I_{OH} = -24 \text{mA}$	2.2		V	
			$V_{CC} = 2.7V \text{ to } 3.6V$	$I_{OL} = 100 \mu A$		0.2		
V	Output Low Vo	lto co	$V_{CC} = 2.7V$	$I_{OL} = 12mA$		0.4		
V_{OL}	Output Low Vo	onage	N - 2N	$I_{OL} = 12 \text{mA}$		0.4	†	
			$V_{CC} = 3V$	$I_{OL} = 24 \text{mA}$		0.55	1	
		Control Inputs	$V_{CC} = 0V \text{ to } 3.6V$	$V_{\rm I} = 0V \text{ to } 5.5V$		±5		
${ m I_I}$	Input Leakage Current	Data Inputs	$V_{CC} = 3.6V$	$V_{\rm I} = 5.5 V$				
1				$V_{I} = V_{CC}$		±5		
				$V_{I} = GND$				
		V = 3V	$V_{I} = 0.8V$	75				
$I_{I(HOLD)}$	I _{I(HOLD)} Data Input Hold	d Current	$V_{CC} = 3V$	$V_{I} = 2V$	-75			
	$V_{CC} = 3.6V^{(6)}$	$V_{I} = 0 \text{ to } 3.6V$		±500				
I_{OFF}	Power Off Out Leakage Curre		$V_{CC} = 0V$	$V_{\rm I}$ or $V_{\rm O} = 0$ V to 5.5V		±5	μА	
I_{OZ}	3-State Output Current	Leakage	$V_{CC} = 2.7V \text{ to } 3.6V$	$V_O = 0V$ to 5.5V		±5		
I _{OZPU}	Power-Up 3-S Current	tate	$V_{CC} = 0V \text{ to } 1.5V$	$V_O = 0.5V$ to 5.5V, OE = don't care		±5		
I _{OZPD}	Power-Down Current	3-State	$V_{CC} = 1.5 V \text{ to } 0 V$	$V_O = 0.5V$ to 5.5V, OE = don't care		±5		
I _{CC}	Quiescent Pow Current	er Supply	$V_{CC} = 2.7V \text{ to } 3.6V$	$\frac{V_{I} = V_{CC} \text{ or GND}}{3.6V \le V_{I} \le 5.5V} I_{O} = 0$		100		
ΔI_{CC}	Increase in I _{CC}		$V_{CC} = 3V \text{ to } 3.6V$	One input at V_{CC} - 0.6 $V^{(7)}$ Other inputs at V_{CC} or GND		200		

Notes: 6. This is the maximum bus-hold dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

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^{7.} This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



Capacitance

Parameters	Description	Test Conditions	Typ. ⁽⁸⁾	Units
C_{IN}	Input Capacitance	$V_{CC} = 3.3V$, $V_I = V_{CC}$ or GND	3.0	
C _{OUT}	Output Capacitance	$V_{CC} = 3.3V$, $V_O = V_{CC}$ or GND	6.2	pF
C _{PD}	Power Dissipation Capacitance (9)	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC} , $f=10$ MHz	28	

Notes:

- 8. All typical values are measured at $V_{CC} = 3.3V$, $T_A = 25$ °C.
- 9. C_{PD} is defined as the value of the internal equivalent capacitance withic is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle, C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD} = (C_{PD})(V_{CC})(f_{IN})+(I_{CC}static).

Switching Characteristics Over Operating Range

		E	То	$V_{\rm CC} = 3.3 \text{V} \pm 0.3 \text{V}$		$V_{\rm CC} = 2.7 V$																				
Parameters	Description	(Input)	From (Output) (Output)	$C_L = 50$ pF, 1	R _L = 500Ohm	$C_L = 50$ pF, I	R _L = 500Ohm	Units																		
				Min.	Max.	Min.	Max.																			
t _{PLH}	D (D)			1.0	5.2	1.0	5.8																			
t _{PHL}	Propagation Delay	A	Y	1.0	5.2	1.0	5.8																			
t _{PZH}	Output Enable Time	OE	Y	1.0	5.8	1.0	6.8																			
t _{PZL}	Output Enable Time	OE	OE	OE	OE	OE	OL	OL	OL		OL	OE	OE	OE		OL	OL	OL	OL	OE		1.0	5.8	1.0	6.8	ns
t _{PHZ}	Output Disable Time	OE	Y	1.0	4.6	1.0	4.8																			
t _{PLZ}	Output Disable Time	OE	OE	OE	OE	I	1.0	4.6	1.0	4.8																
t _{SK(O)}	Output to Output Skew ⁽¹⁰⁾				0.5																					

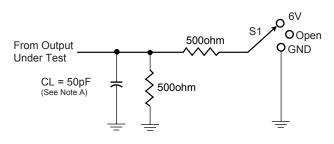
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Notes:

10. Skew between any two outputs, switching in the same direction.

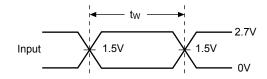


PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.7V$ and $3.3V \pm 0.3V$

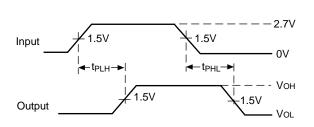


Test	S1
tpLH/tpHL	Open
tpLZ/tpZL	6V
tpHZ/tpZH	GND

Load Circuit



Voltage Waveforms Pulse Duration



Voltage Waveforms Propagation Delay Times

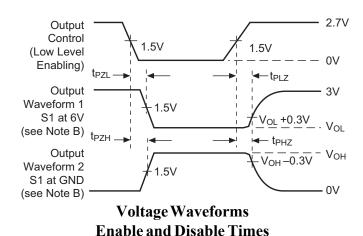


Figure 1. Load Circuit and Voltage Waveforms

Notes:

- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input impulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50ohm, $t_R \leq$ 2.5ns, $t_F \leq$ 2.5ns.

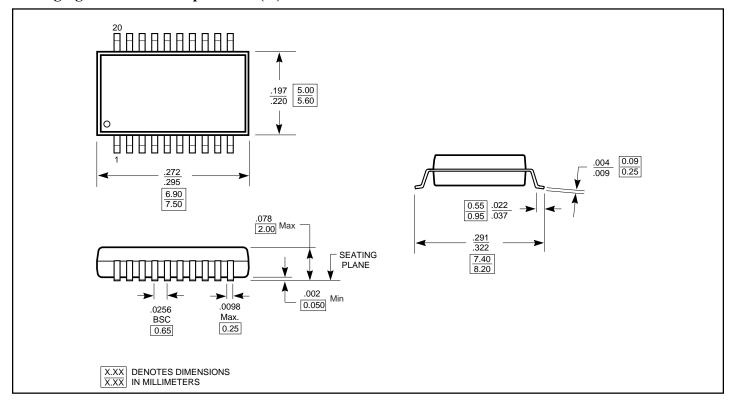
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D. The outputs are measured one at a time with one transition per measurement.

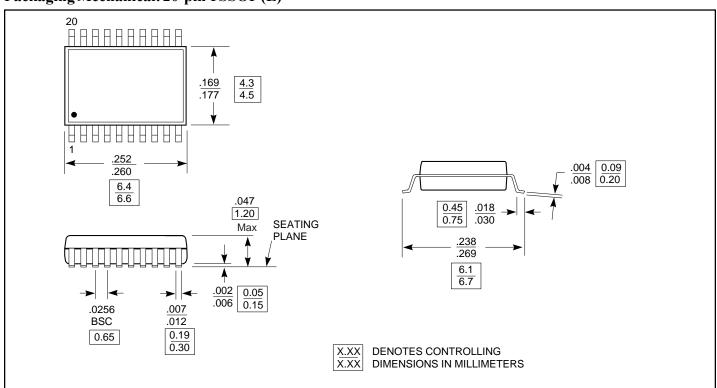
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Packaging Mechanical: 20-pin SSOP (H)

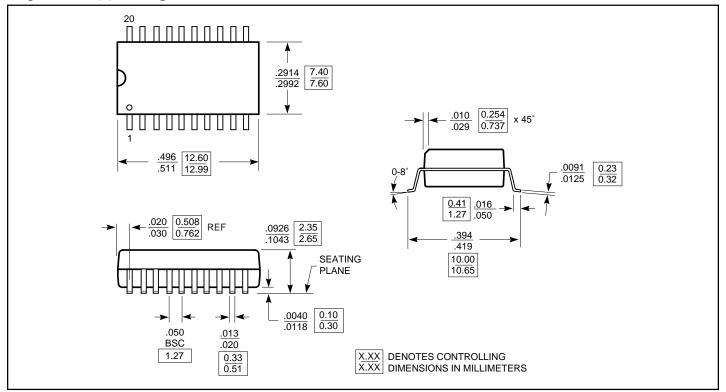


Packaging Mechanical: 20-pin TSSOP(L)





20-pin SOIC (S) Package



Ordering Information

Ordering Data	Description
PI74LVTCH244H	20-pin, 209-mil wide plastic SSOP
PI74LVTCH244L	20-pin, 173-mil wide plastic TSSOP
PI74LVTCH244S	20-pin, 300-mil wide plastic SOIC

Notes:

1. Thermal characteristics can be found on the company web site at http://www.pericom.com/packaging/mechanicals.php

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